

Title (en)

High-strength hot rolled steel plate and manufacturing method thereof

Title (de)

Widerstandsfähige heißgewalzte Stahlplatte und Herstellungsverfahren dafür

Title (fr)

Plaque d'acier laminée à chaud haute résistance et son procédé de fabrication

Publication

**EP 1990430 B1 20110615 (EN)**

Application

**EP 08154615 A 20080416**

Priority

JP 2007108759 A 20070417

Abstract (en)

[origin: EP1990430A1] The present invention provides a new high-strength and Si-Cr containing hot rolled steel plate provided with higher strength as well as excellent workability and a method for manufacturing the steel plate. The high-strength steel plate can be obtained by controlling the particle size of prior austenite to be 10µm or less, and properly selecting the cooling temperature. The steel plate obtained includes a retained austenite phase in a volume fraction of 5% to 20%; a martensite phase in a volume fraction equal to or less than 10%; and a bainite phase in the remaining volume fraction. The particle size of the retained austenite particle is 1µm or less and the retained austenite particles are dispersed uniformly.

IPC 8 full level

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